



Product Change Notification / LIAL-08RPHO713

Date:

15-Feb-2021

Product Category:

Ethernet PHYs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3459.002 Final Notice: Qualification of MTAI as an additional assembly site for selected Micrel automotive products available in 32L VQFN (5x5x0.9mm) package.

Affected CPNs:

[LIAL-08RPHO713_Affected_CPN_02152021.pdf](#)

[LIAL-08RPHO713_Affected_CPN_02152021.csv](#)

Notification Text:

PCN Status: Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MTAI as an additional assembly site for selected Micrel automotive products available in 32L VQFN (5x5x0.9mm) package.

Pre Change:

Assembled at ASE using gold (Au) bond wire, EN-4900F die attach material, G631H molding compound material, Ag ring plated lead frame DAP surface prep in 138 x 138 mils lead frame paddle size and without lead lock lead frame

Post Change:

Assembled at ASE using gold (Au) bond wire, EN-4900F die attach material, G631H molding compound material, Ag ring

plated lead frame DAP surface prep in 138 x 138 mils lead frame paddle size and without lead lock lead frame. Or Assembled at MTAI using gold (Au/2N) bond wire, 3280 die attach material, G700LTD molding compound material, Ag spot plated lead frame DAP surface prep in 150 x 150 mils lead frame paddle size and with lead lock lead frame.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Microchip Technology Thailand (HQ)MTAI
Wire material	Au	Au	Au/2N
Die attach material	EN-4900F	EN-4900F	3280
Molding compound material	G631H	G631H	G700LTD
Lead frame material	C194	C194	C194
Lead Frame DAP Surface Prep	Ag ring plated	Ag ring plated	Ag spot plated
Lead Frame Paddle size	138 x 138 mils	138 x 138 mils	150 x 150 mils
Lead frame lead-lock	No	No	Yes
	See Pre and Post Change attachment for lead frame comparison.		

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:March 15, 2021 (date code: 2112)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2021				March 2021				
Workweek	06	07	08	09	10	11	12	13	14

Qual Report Availability			X						
Final PCN Issue Date			X						
Estimated Implementation Date							X		

Method to Identify Change:Traceability code.

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:February 15, 2021: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on March 15, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-08RPHO713_Qual Report.pdf](#)

[PCN_LIAL-08RPHO713_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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